					1		ONS										
LTR			DES	SCRIPTIO	N					DA	TE (YF	R-MO-D	DA)		APPF	ROVED	
А	Add case outline 2 changes throughout		ce types	01 and 02	. Upda	te form	at. Edi	torial			89-1	1-07			M. A	. Frye	
В	Changes to large-s Changes IAW NO	signal vol <sup>.</sup> R 5962-R	tage gaii 193-93.	n test and	to the c	output v	oltage	swing t	est.		93-0	8-26			M. A	. Frye	
С	Add case outline K Add delta test limit			plate to add	d one-p	art part	numbe	ers.			96-1	1-25			R. N	1onnin	
D	Add radiation hard	ness requ	uirement	ts. Update	boilerp	olate	rrp				98-0	6-19			R. N	Ionnin	
E	Change to the slev			=							00-1	0-04			R. N	Ionnin	
F	Add case outline E 1.2.4, 1.3, 3.2.3, fig requirementsrrp	gure 1, ar	ve radiati nd table	ion exposu IIA. Upda	te boile	uit. Cha rplate te	anges r o reflec	nade to t currei	o nt		03-0	3-19			R. M	1onnin	
G	Update drawing to paragraphs. –rrp	current r	equirem	ents. Dele	eted un	used gr	oup E I	oilerpl	ate		11-0	4-06			C. :	Saffle	
Н	Add device types ( 1.5, Table I, figure	)3 and 04 1, Table	4 tested a IIB, 4.4.4	at low dos 4.1 ro	e rate.	Make c	changes	s to 1.2	.2,		11-1	1-16			C. :	Saffle	
J	Update document	paragrap	hs to cu	rrent MIL-F	PRF-38	5345 re	equirem	ents. ·	ro		17-1	1-06			C. S.	AFFLE	
THE ORIGINAI REV SHEET REV SHEET	L FIRST SHEET OF		AWING F	HAS BEEN	N REPL	ACED.											
REV SHEET REV		THIS DRA	AWING F	HAS BEEN	I REPL	ACED.	J			J	J	J	J	J			
REV SHEET REV SHEET								J 5	J 6	J 7	J 8	J	J 10	J 11			
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A		REV	T ARED B	J J 1	J	J	J		6	7 DLA I	8 LAND	9 AND	10 MAF	11 <b>RITIM</b>			
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A		REV SHEE PREPA Gary CHECI	T ARED B	J 1 Y	J	J	J		6 CC	7 DLA I DLUM	8 LAND BUS,	9	10 MAF D 432	11 RITIM 218-3	990		
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A STA MICRO DR/ THIS DRAWI	NDARD OCIRCUIT AWING	REV SHEE PREPA Gary CHECI Ray M	T ARED B' Zahn KED BY	y Y	J	J	J 4 MIC	5 ROC	6 CC http:	7 DLA I DLUM //www	8 BUS, w.dla.	9 AND OHIC mil/la	10 MAF D 432 andar	11 218-33 0dma	990 ritime	-	
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A STA MICRO DRA THIS DRAWII FOR U DEPA AND AGEI		REV SHEE PREP/ Gary CHECI Ray M APPRO Micha	T ARED B' Zahn KED BY Monnin OVED B' ael A. Fry	y Y	J 2	J	J 4 MIC HAI	5 ROC	6 CC http: VIRCU	7 DLA I DLUM //www	8 BUS, w.dla	9 AND OHIC mil/la	10 MAF D 432 Indar	11 RITIM 218-3 Idma	990 ritime		 
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A STA MICRO DEPA THIS DRAWII FOR U DEPA AND AGEI DEPARTMEI	NDARD OCIRCUIT AWING NG IS AVAILABLE JSE BY ALL ARTMENTS NCIES OF THE	REV SHEE PREP/ Gary CHECI Ray M APPRO Micha	T ARED B' Zahn KED BY Monnin OVED B' ael A. Fry	Y Y PROVAL I 38-08-18	J 2	J	J 4 MIC HAI	5 ROC RDEN PLIFI	6 CC http: CIRCU NED, ER, I CA	7 DLA I DLUM //www	8 BUS, w.dla.	9 AND OHIC mil/la	10 MAF D 432 Indan	11 RITIM 218-3 Idma	990 ritime N ERA	TION	AL

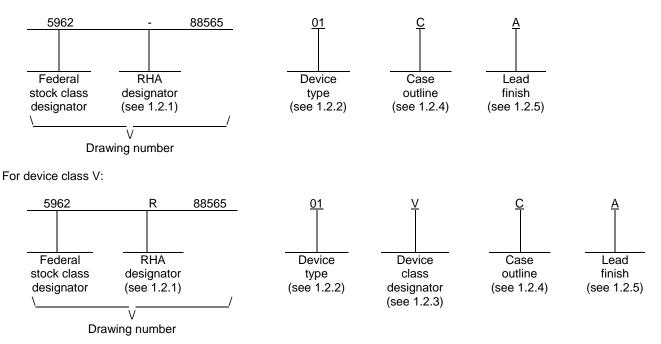
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### 1. SCOPE

1.1 <u>Scope</u>. This drawing documents two product assurance class levels consisting of high reliability (device class Q and M) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels is reflected in the PIN.

1.2 <u>PIN</u>. The PIN is as shown in the following examples.

For device class M and Q:



1.2.1 <u>RHA designator</u>. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. Device class M RHA marked devices meet the MIL-PRF-38535, appendix A specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 <u>Device type(s)</u>. The device type(s) identify the circuit function as follows:

Device type	Generic number	Circuit function
01	OP-470A	Very low noise, quad, operational amplifier
02	OP-471A	High speed, low noise, quad, operational amplifier
03	OP-470A	Very low noise, quad, operational amplifier
04	OP-471A	High speed, low noise, quad, operational amplifier

1.2.3 <u>Device class designator</u>. The device class designator is a single letter identifying the product assurance level as listed below. Since the device class designator has been added after the original issuance of this drawing, device classes M and Q designators will not be included in the PIN and will not be marked on the device.

Device class	Device requirements documentation							
Μ		Vendor self-certification to the requirements for MIL-STD-883 compliant, non- JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A						
Q or V	Certification a	Certification and qualification to MIL-PRF-38535						
STANDA MICROCIRCUIT		SIZE A		5962-88565				
DLA LAND AND COLUMBUS, OHIC			REVISION LEVEL	SHEET 2				

1.2.4 <u>Case outline(s)</u>. The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	Terminals	Package style
С	GDIP1-T14 or CDIP2-T14	14	Dual-in-line
D	GDFP1-F14 or CDFP2-F14	14	Flat pack
2	CQCC1-N20	20	Square leadless chip carrier
3	CQCC1-N28	28	Square leadless chip carrier
К	GDFP2-F24 or CDFP3-F24	24	Flat pack

1.2.5 <u>Lead finish</u>. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

1.3 Absolute maximum ratings. 1/

Supply voltage (VCC)		±18 V dc	
Differential input voltage		±1 V dc <u>2</u> /	
Differential input current		±25 mA <u>2</u> /	
Input voltage			
Output short circuit duration			
Storage temperature range			
Lead temperature (soldering, 60 seconds)		+300°C	
Power dissipation (PD):			
Cases C and 2			
Case D			
Case 3 Case K			
Maximum junction temperature (TJ)			
Thermal resistance, junction-to-case (θJC)			5
Thermal resistance, junction-to-ambient ( $\theta$ JA):			
Cases C and 2		100°C/W	
Case D			
Case 3		110°C/W	
Case K		69°C/W	
1.4 Recommended operating conditions.			
Ambient operating temperature range (TA)		55°C to +125°C	
Supply voltage (VCC)		±15 V	
1.5 Radiation features.			
Device types 01 and 02: Maximum total dose available (dose rate = 50 – 300 rads Device types 03 and 04:	s(Si)/s)	100 krads(Si) <u>3</u> /	
Maximum total dose available (dose rate ≤ 10 mrads(Si)/	/s)	50 krads (Si) <u>4</u> /	
$\frac{1}{1}$ Stresses above the absolute maximum rating may cause per	manent damage t	o the device. Extended op	eration at the
maximum levels may degrade performance and affect reliabil		, i	
2/ The inputs are protected by back-to-back diodes. Current lim			/e low noise
performance. If the differential input voltage exceeds $\pm 1$ V, the			
<u>3</u> / Device types 01 and 02 may be dose rate sensitive in a spac			
effects. Radiation end point limits for the noted parameters a MIL-STD-883, method 1019, condition A.	are guaranteed on	ly for the conditions specifie	eain
$\underline{4}$ / For device type 03 and 04, radiation end point limits for the n	oted parameters	are guaranteed for the cond	titions specified
in MIL-STD-883, method 1019, condition D.		are guaranteed for the cont	
STANDARD	SIZE		
	A		5962-88565
DLA LAND AND MARITIME			
COLUMBUS, OHIO 43218-3990			SHEET 2
		J	3
DSCC FORM 2234			

APR 97

### 2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

#### DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.

MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <u>http://quicksearch.dla.mil</u> or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

#### 3. REQUIREMENTS

3.1 <u>Item requirements</u>. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.

3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.

3.2.1 <u>Case outlines</u>. The case outlines shall be in accordance with 1.2.4 herein.

3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 1.

3.2.3 <u>Radiation exposure circuit</u>. The radiation exposure circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing and acquiring activity upon request.

3.3 <u>Electrical performance characteristics and postirradiation parameter limits</u>. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table IIA. The electrical tests for each subgroup are defined in table I.

3.5 <u>Marking</u>. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-88565
DLA LAND AND MARITIME		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43218-3990		J	4

	TA	ABLE I. Electric	al performance	characterist	<u>tics</u> .				
Test	Symbol	$\begin{array}{c c} & Conditions \ \underline{1}/ \ \underline{2}/\\ -55^{\circ}C \leq TA \leq +125^{\circ}C\\ unless \ otherwise \ specified \end{array}$		Group A subgroup		Lim	its	s Unit	
						Min	Max		
Input offset voltage	Vio			1	01, 03		±0.4	mV	
			. <u></u>	2, 3			±0.6	_	
			M,D,P,L,R	1	01		±0.6	_	
			M,D,P,L	1	03		±0.6		
				1	02, 04		±0.8		
				2, 3			±1.2		
			M,D,P,L,R	1	02		±1.0		
			M,D,P,L	1	04		±1.0		
Input offset current	lio	VCM = 0 V		1	All		±10	nA	
				2, 3			±20		
			M,D,P,L,R	1	01, 02		50	-	
			M,D,P,L	1	03, 04		50		
Input bias current	lıB	VCM = 0 V		1	All		±25	nA	
				2, 3			±50	-	
			M,D,P,L,R	1	01, 02		±500	_	
			M,D,P,L	1	03, 04		±500	_	
Input noise voltage	En	f <sub>0</sub> = 1 Hz to 1		7	01, 03		110	nV	
		TA = +25°C			02, 04		265	RMS	
Large-signal voltage gain	Avs	$V_0 = \pm 10 V_0$		4	01, 03	1000		V/mV	
		RL = 10 kΩ		5, 6		750			
			M,D,P,L,R	4	01	100		_	
			M,D,P,L	4	03	100		_	
		Vo = ±10 V,		4	01, 03	500		_	
		$RL = 2 k\Omega$	<u>o</u> ,	5, 6		400		_	
		$V_0 = \pm 10 V$ ,		4	02, 04	500			
		$RL = 10 k\Omega$		5, 6		375			
		RL = 10 KS2	M,D,P,L,R	4	02	50		_	
			M,D,P,L	4	02	50		_	
See footnotes at end of table.		<u> </u>		1		L I.		1	
STA MICROCIRC	NDARD	WING		SIZE <b>A</b>			596	2-88565	
DLA LAND / COLUMBUS,	AND MARITI	ME		F	REVISION LEV	EL	SHEE	⊤ 5	

	TABLE I.	Electrical perf	ormance chara	<u>cteristics</u> – Cor	ntinued.			
Test	Symbol	Conditions $1/2/$ -55°C $\leq$ TA $\leq$ +125°C unless otherwise specified		Group A subgroups	Device type		mits	Unit
						Min	Max	
Large-signal voltage gain	Avs	VO = ±10 V,	<u>3</u> /	4	02, 04	350		V/mV
		$RL = 2 k\Omega$		5, 6		250		
Output voltage swing	VOP	$R_L = 2 k\Omega \frac{3}{2}$	1	4, 5, 6	All	±12		V
Supply current <u>4</u> /	Is	No load		1, 2, 3	All		11	mA
			M,D,P,L,R	1	01, 02		11	
			M,D,P,L	1	03, 04		11	
Slew rate	SR	AVCL = +21,	RL = 10 kΩ,	7	01, 03	1.4		V/µs
		TA = +25°C	<u>3</u> /		02, 04	6.5		
Common-mode rejection	CMR	VCM = IVR =	±11 V <u>3</u> / <u>5</u> /	1	01, 03	110		dB
				2, 3		100		
				1	02, 04	105		
				2, 3		100		
Power supply rejection ratio	PSRR	VCC = ±4.5 V	′ to ±18 V <u>3</u> /	1	01, 03		1.8	μV/V
				2, 3	]		5.6	
				1	02, 04		5.6	
				2, 3			10	

Device types 01 and 02 supplied to this drawing has been characterized through all levels M, D, P, L, R of irradiation. 1/ Device types 03 and 04 supplied to this drawing has been characterized through all levels M, D, P, L of irradiation. However, device types 01 and 02 is only tested at the "R" level and device types 03 and 04 is only tested at the "L" level. Pre and Post irradiation values are identical unless otherwise specified in Table I. When performing post irradiation electrical measurements for any RHA level, TA = +25°C. VCC =  $\pm$ 15 V, RS = 50  $\Omega$ .

- For device types 01 and 02, these parts may be dose rate sensitive in a space environment and may demonstrate <u>2</u>/ enhanced low dose rate effects. Radiation end point limits for the noted parameters are guaranteed only for the conditions specified in MIL-STD-883, method 1019, condition A for device types 01 and 02 and condition D for device types 03 and 04. Device types 03 and 04, have been tested at low dose rate.
- This parameter is not tested post-irradiation. 3/
- IS limit equals the total of all amplifiers. <u>4</u>/
- <u>5</u>/ IVR is defined as the VCM range used for the CMR test.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-88565
DLA LAND AND MARITIME		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43218-3990		J	6

Device types			ind 03, 04				
Case outlines	C and D	K	2	3			
Terminal number		Terminal symbol					
1	OUT A	OUT A	NC	NC			
2	-IN A	-IN A	OUT A	OUT A			
3	+IN A	NC	-IN A	-IN A			
4	+VCC	NC	+IN A	NC			
5	+IN B	+IN A	NC	NC			
6	-IN B	+VCC	+VCC	+IN A			
7	OUT B	+IN B	NC	NC			
8	OUT C	NC	+IN B	+VCC			
9	-IN C	NC	-IN B	NC			
10	+IN C	NC	OUT B	+IN B			
11	-Vcc	-IN B	NC	NC			
12	+IN D	OUT B	OUT C	NC			
13	-IN D	OUT C	-IN C	-IN B			
14	OUT D	-IN C	+IN C	OUT B			
15		NC	NC	NC			
16		NC	-Vcc	OUT C			
17		NC	NC	-IN C			
18		+IN C	+IN D	NC			
19		-Vcc	-IN D	NC			
20		+IN D	OUT D	+IN C			
21		NC		NC			
22		NC		-Vcc			
23		-IN D		NC			
24		OUT D		+IN D			
25				NC			
26				NC			
27				-IN D			
28				OUT D			

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-88565
DLA LAND AND MARITIME		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43218-3990		J	7

FIGURE 1. Terminal connections.

3.5.1 <u>Certification/compliance mark</u>. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.

3.6 <u>Certificate of compliance</u>. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DLA Land and Maritime-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.

3.7 <u>Certificate of conformance</u>. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 <u>Notification of change for device class M</u>. For device class M, notification to DLA Land and Maritime-VA of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change that affects this drawing.

3.9 <u>Verification and review for device class M</u>. For device class M, DLA Land and Maritime, DLA Land and Maritime 's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

3.10 <u>Microcircuit group assignment for device class M</u>. Device class M devices covered by this drawing shall be in microcircuit group number 49 (see MIL-PRF-38535, appendix A).

### 4. VERIFICATION

4.1 <u>Sampling and inspection</u>. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 <u>Screening</u>. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.

### 4.2.1 Additional criteria for device class M.

- a. Burn-in test, method 1015 of MIL-STD-883.
  - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015.
  - (2)  $TA = +125^{\circ}C$ , minimum.
- b. Interim and final electrical test parameters shall be as specified in table IIA herein.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-88565
DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990		REVISION LEVEL J	SHEET 8

Test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)	Subgr (in accorda MIL-PRF-385	ance with
	Device class M	Device class Q	Device class V
Interim electrical parameters (see 4.2)	1	1	1
Final electrical parameters (see 4.2)	1,2,3,4,5,6 <u>1</u> /	1,2,3,4,5,6 <u>1</u> /	1,2,3,4, <u>1/ 2</u> / 5,6
Group A test requirements (see 4.4)	1,2,3,4,5,6,7	1,2,3,4,5,6,7	1,2,3,4,5,6,7
Group C end-point electrical parameters (see 4.4)	1	1	1 <u>2</u> /
Group D end-point electrical parameters (see 4.4)	1	1	1
Group E end-point electrical parameters (see 4.4)			1, 4

TABLE IIA. Electrical test requirements.

 $\underline{1}$  PDA applies to subgroup 1.  $\underline{2}$  Delta limits as specified in table IIB shall be required where specified, and the delta limits shall be computed with reference to the previous interim electrical parameters.

TABLE IIB.	Burn-in and operating life test delta parameter	<u>s</u> . TA = +25°C. <u>1/ 2</u> /

Parameter Devic	Device types	Lir	nit	Delta	
rarameter	Device types	Min	Max	Min	Max
Vos	01, 03		0.4 mV		100 μV
	02, 04		0.8 mV		250 μV
los	01, 03		10 nA		5 nA
	02, 04		10 nA		5 nA
lв	01, 03		±25 nA		5 nA
	02, 04		±25 nA		5 nA

 $\underline{1}'$  Deltas are performed at room temperature.  $\underline{2}'$  240 hour burn-in and 1,000 hour operating group C life test.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		5962-88565
		REVISION LEVEL J	SHEET 9

- 4.2.2 Additional criteria for device classes Q and V.
  - a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
  - b. Interim and final electrical test parameters shall be as specified in table IIA herein.
  - c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.

4.3 <u>Qualification inspection for device classes Q and V</u>. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 <u>Conformance inspection</u>. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections and as specified. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

### 4.4.1 Group A inspection.

- a. Tests shall be as specified in table IIA herein.
- b. Subgroups 8, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.

4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table IIA herein.

- 4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:
  - a. Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
  - b.  $TA = +125^{\circ}C$ , minimum.
  - c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-88565
DLA LAND AND MARITIME		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43218-3990		J	10

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.4 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).

- a. End-point electrical parameters shall be as specified in table IIA herein.
- b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535, appendix A for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at TA = +25°C ±5°C, after exposure, to the subgroups specified in table IIA herein.

4.4.4.1 <u>Total dose irradiation testing</u>. Total dose irradiation testing shall be performed in accordance with MIL-STD-883 method 1019, condition A for device types 01 and 02, condition D for device types 03 and 04 and as specified herein.

## 5. PACKAGING

5.1 <u>Packaging requirements</u>. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

## 6. NOTES

6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractorprepared specification or drawing.

6.2 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.3 <u>Record of users</u>. Military and industrial users should inform DLA Land and Maritime when a system application requires configuration control and which SMD's are applicable to that system. DLA Land and Maritime will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DLA Land and Maritime-VA, telephone (614) 692-8108.

6.4 <u>Comments</u>. Comments on this drawing should be directed to DLA Land and Maritime-VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0540.

6.5 <u>Abbreviations, symbols, and definitions</u>. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

### 6.6 Sources of supply.

6.6.1 <u>Sources of supply for device classes Q and V</u>. Sources of supply for device classes Q and V are listed in MIL-HDBK-103 and QML-38535. The vendors listed in MIL-HDBK-103 and QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DLA Land and Maritime-VA and have agreed to this drawing.

6.6.2 <u>Approved sources of supply for device class M</u>. Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DLA Land and Maritime-VA.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-88565
DLA LAND AND MARITIME		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43218-3990		J	11

## STANDARD MICROCIRCUIT DRAWING BULLETIN

# DATE: 17-11-06

Approved sources of supply for SMD 5962-88565 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DLA Land and Maritime-VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DLA Land and Maritime maintains an online database of all current sources of supply at <a href="https://landandmaritimeapps.dla.mil/Programs/Smcr/">https://landandmaritimeapps.dla.mil/Programs/Smcr/</a>.

Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /
5962-8856501CA	24355 (2)	OP-470AY/883C
5962-88565012A	24355 (2)	OP-470ARC/883C
5962-88565013A	<u>3</u> /	OP-470ATC/883C
5962-8856502CA	24355 (2)	OP-471AY/883C
5962-88565022A	24355 (2)	OP-471ARC/883C
5962-88565023A	24355 (2)	OP-471ATC/883C
5962-8856501VCA	<u>3</u> /	OP470AY/QMLV
5962-8856501V2A	<u>3</u> /	OP470ARC/QMLV
5962-8856501VKA	<u>3</u> /	OP470AN/QMLV
5962-8856502VCA	<u>3</u> /	OP471AY/QMLV
5962-8856502VDA	<u>3</u> /	OP471AM/QMLV
5962-8856502V2A	<u>3</u> /	OP471ARC/QMLV
5962-8856502VKA	<u>3</u> /	OP471AN/QMLV
5962R8856501VCA	24355 (4)	OP470AY/QMLR
5962R8856501V2A	24355 (4)	OP470ARC/QMLR
5962R8856501VKA	24355(4)	OP470AN/QMLR
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See footnotes at end of table.

## STANDARD MICROCIRCUIT DRAWING BULLETIN - CONTINUED

Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /
5962R8856502VCA	24355 (4)	OP471AY/QMLR
5962R8856502VDA	24355 (4)	OP471AM/QMLR
5962R8856502V2A	<u>3</u> /	OP471ARC/QMLR
5962R8856502VKA	24355 (4)	OP471AN/QMLR
5962L8856503VCA	24355 (4)	OP470AY/QMLL
5962L8856504VDA	24355 (4)	OP471AM/QMLL

DATE: 17-11-06

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- <u>2</u>/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ Not available from an approved source of supply.

Vendor CAGE number	Vendor name and address	
24355	Analog Devices ( Route 1 Industria P.O. Box 9106 Norwood, MA 02 Point of contact:	Í Park
24355	Analog Devices Route 1 Industria P.O. Box 9106 Norwood, MA 02 Point of contact:	Ì Park

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.